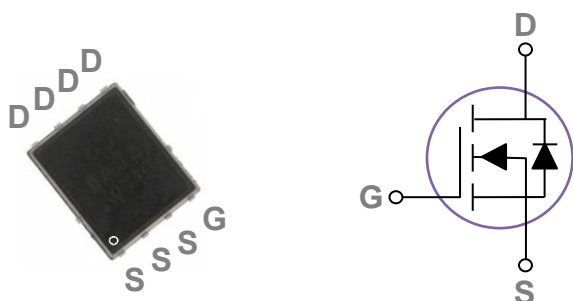


40V N-Channel MOSFETs

General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

PPAK5×6 Pin Configuration



BV_{DSS}	$R_{DS(ON)Max.}$	I_D
40V	5.5m Ω	90A

Features

- 40V, 90A, $R_{DS(ON)Max.}=5.5m\Omega@V_{GS} = 10V$
- Improved dv/dt capability
- Fast switching
- Green Device Available

Applications

- Notebook
- Load Switch
- LED applications
- Hand-Held Device

Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	40	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Drain Current – Continuous ($T_c=25^\circ\text{C}$)	90	A
	Drain Current – Continuous ($T_c=100^\circ\text{C}$)	57	A
I_{DM}	Drain Current – Pulsed ¹	360	A
E_{AS}	Single Pulse Avalanche Energy ²	80	mJ
I_{AS}	Single Pulse Avalanche Current ²	40	A
P_D	Power Dissipation ($T_c=25^\circ\text{C}$)	142	W
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$

Note 1: Exceed these limits to damage to the device.

Note 2: Exposure to absolute maximum rating conditions may affect device reliability.

Electrical Characteristics ($T_J=25\text{ }^\circ\text{C}$, unless otherwise

noted) Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	40			V
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=40V, V_{GS}=0V, T_J=25^\circ C$			1	μA
		$V_{DS}=32V, V_{GS}=0V, T_J=85^\circ C$			10	μA
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$			± 100	nA

On Characteristics

$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=10V, I_D=24A$		4.8	5.5	$m\Omega$
		$V_{GS}=4.5V, I_D=12A$		6.2	7.2	$m\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu A$	1.2	1.6	2.5	V
$\Delta V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient			-4		$mV/^\circ C$
g_{fs}	Forward Transconductance	$V_{DS}=5V, I_D=20A$		70		S

Dynamic and switching Characteristics

Q_g	Total Gate Charge ^{3, 4}	$V_{DS}=20V, V_{GS}=10V, I_D=15A$		20		nC
Q_{gs}	Gate-Source Charge ^{3, 4}			5.5		
Q_{gd}	Gate-Drain Charge ^{3, 4}			3		
$T_{d(on)}$	Turn-On Delay Time ^{3, 4}	$V_{DD}=15V, V_{GS}=10V, R_G=3.3\Omega$ $I_D=1A$		7.5		ns
T_r	Rise Time ^{3, 4}			2		
$T_{d(off)}$	Turn-Off Delay Time ^{3, 4}			23		
T_f	Fall Time ^{3, 4}			3		
C_{iss}	Input Capacitance	$V_{DS}=20V, V_{GS}=0V, F=1MHz$		1480		pF
C_{oss}	Output Capacitance			245		
C_{rss}	Reverse Transfer Capacitance			13		
R_g	Gate resistance	$V_{GS}=0V, V_{DS}=0V, F=1MHz$		0.8		Ω

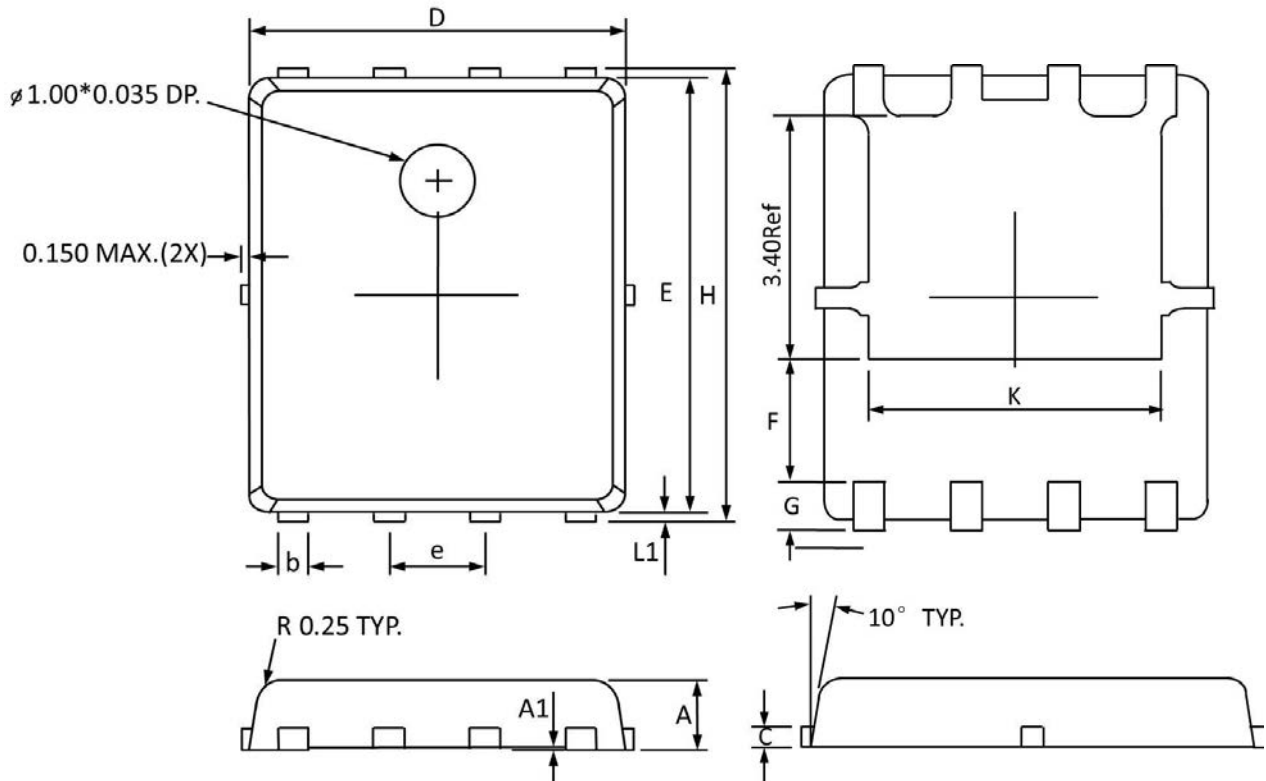
Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Continuous Source Current	$V_G=V_D=0V, \text{Force Current}$			90	A
I_{SM}	Pulsed Source Current				180	A
V_{SD}	Diode Forward Voltage	$V_{GS}=0V, I_S=1A, T_J=25^\circ C$			1	V

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. $V_{DD}=25V, V_{GS}=10V, L=0.1mH, I_{AS}=39A, R_G=25\Omega, \text{Starting } T_J=25^\circ C$.
3. The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.
4. Essentially independent of operating temperature.

PPAK5X6 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.800	1.000	0.032	0.039
A1	0.000	0.005	0.000	0.000
b	0.350	0.490	0.014	0.019
C	0.254 Ref		0.254 Ref	
D	4.900	5.100	0.193	0.200
E	5.700	5.900	0.225	0.232
e	1.27 BSC		1.27 BSC	
F	1.400 Ref		1.400 Ref	
G	0.600 Ref		0.600 Ref	
H	5.950	6.200	0.235	0.244
L1	0.100	0.180	0.004	0.007
K	4.000 Ref		4.000 Ref	